

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. – 18. (Cancelled)

19. (Currently Amended) An IC chip comprising at least one externally and selectively cuttable member having at least one cuttable section, the cuttable member including a multiplicity of cuttable points, wherein

said cuttable member remain cut open so long as at least one cuttable point remains cut open, and wherein

said cuttable member includes a multiplicity of cuttable sections which are coupled at one ends thereof with the same electric potential and coupled at the other ends thereof with ~~respective logic circuits~~ a logic circuit, which function as if said cuttable sections were physically connected in series.

20. (Previously presented) The IC chip according to claim 19, wherein said cuttable sections have a linear portion of a uniform width.

21. (Previously presented) The IC chip according to claim 19, wherein each of said cuttable sections has a narrow portion formed between two wide portions.

22. (Currently Amended) A semiconductor device, comprising:
an IC chip having

at least one externally and selectively ~~cut~~ cuttable member including at least one ~~cut~~ cuttable section, the ~~cut~~ cuttable member including a multiplicity of ~~cut~~ cuttable points, said ~~cut~~ cuttable member working normally when at least one of said ~~cut~~ cuttable points remains cut open, and

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bumps formed on the same side of the IC chip as the cut member in association with respective ~~cut~~ cuttable points;

a substrate/or another IC chip; and

a connection member made of an anisotropic conductor and sandwiched between said IC chip and said substrate/or another IC chip, wherein said IC chip and said substrate/or another IC chip are pressed together, and wherein

said ~~cut~~ cuttable member includes a multiplicity of ~~cut~~ cuttable sections which are coupled at one ends thereof with the same electric potential and coupled at the other ends thereof with ~~respective logic circuits~~ a logic circuit, which function as if said cuttable sections were physically connected in series.

23. (Previously presented). The semiconductor device according to claim 22 wherein said cut sections have a linear portion of a uniform width.

24. (Previously presented). The semiconductor device according to claim 22 wherein each of said cut sections has a narrow portion between two wide portions.